UNIKC Semiconductor

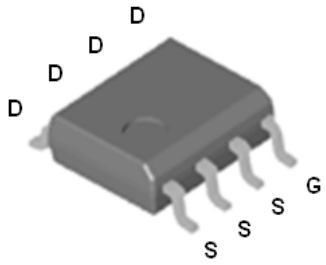
RoHS Compliant

PD0903BVA

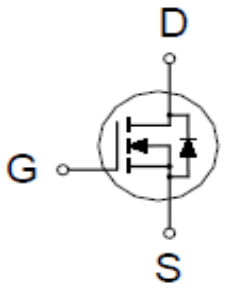
N-Channel Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
30V	9mΩ @V_{GS} = 10V	13A



SOP-8



ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±20	
Continuous Drain Current	T_A = 25 °C	I_D	13	A
	T_A = 70 °C		10	
Pulsed Drain Current[1]		I_{DM}	80	
Avalanche Current		I_{AS}	30	
Avalanche Energy	L =0.1mH	E_{AS}	45	mJ
Power Dissipation	T_A= 25 °C	P_D	2.3	W
	T_A =70 °C		1.5	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE		SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient[2]	Steady-State	$R_{\theta JA}$		55	°C / W
Junction-to-Case	Steady-State	$R_{\theta JC}$		3.7	

[1]Pulse width limited by maximum junction temperature.

[2]The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25° C.The value in any given application depends on the user's specific board design

UNIKC Semiconductor

RoHS Compliant

PD0903BVA
N-Channel Enhancement Mode MOSFET

ELECTRICAL CHARACTERISTICS (T_J = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D = 250μA	30			V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250μA	1	1.7	3	
Gate-Body Leakage	I_{GSS}	V_{DS} = 0V, V_{GS} = ±20V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 24V, V_{GS} = 0V			0.03	mA
		V_{DS} = 20V, V_{GS} = 0V, T_J = 125 °C			10	
On-State Drain Current[1]	$I_{D(ON)}$	V_{DS} = 5V, V_{GS} = 10V	80			A
Drain-Source On-State Resistance[1]	$R_{DS(ON)}$	V_{GS} = 4.5V, I_D = 13A		11.2	13	mΩ
		V_{GS} = 10V, I_D = 13A		7	9	
Forward Transconductance[1]	g_{fs}	V_{DS} = 10V, I_D = 13A		47		S
DYNAMIC						
Input Capacitance	C_{iss}	V_{GS} = 0V, V_{DS} = 15V, f = 1MHz		1570		pF
Output Capacitance	C_{oss}			202		
Reverse Transfer Capacitance	C_{rss}			158		
Gate Resistance	R_g	V_{GS} = 0V,V_{DS} = 0V,f = 1MHz		1.4		Ω
Total Gate Charge[2]	Q_g(V_{GS}=10V)	V_{DS} = 0.5$V_{(BR)DSS}$, I_D = 13A		31		nC
	Q_g(V_{GS}=4.5V)			16		
Gate-Source Charge[2]	Q_{gs}			5.5		
Gate-Drain Charge[2]	Q_{gd}			8		
Turn-On Delay Time[2]	$t_{d(on)}$	V_{DD} = 15V, I_D ≅ 13A,V_{GEN} = 10V, R_G = 6Ω		10.8		nS
Rise Time[2]	t_r			16.8		
Turn-Off Delay Time[2]	$t_{d(off)}$			38.4		
Fall Time[2]	t_f			19.2		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_J = 25 °C)						
Continuous Current[3]	I_S				6	A
Forward Voltage[1]	V_{SD}	I_F = 1A, V_{GS} = 0V		0.8		V
Reverse Recovery Time	t_{rr}	I_F = 13A, dI/dt = 100A / μS		15		nS
Reverse Recovery Charge	Q_{rr}			4		nC

[1]Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

[2]Independent of operating temperature.

[3]Maximum continuous current include Body diode + Shottky

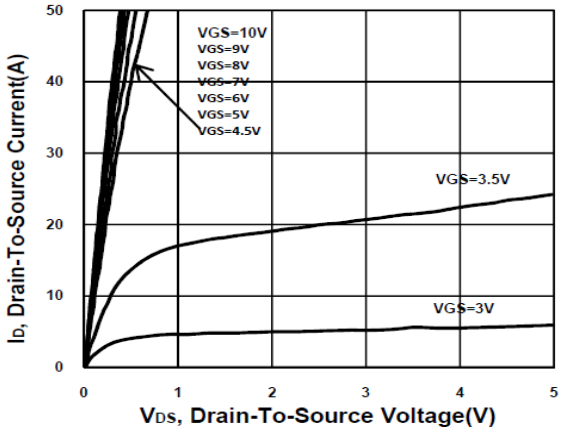
UNIKC Semiconductor

RoHS Compliant

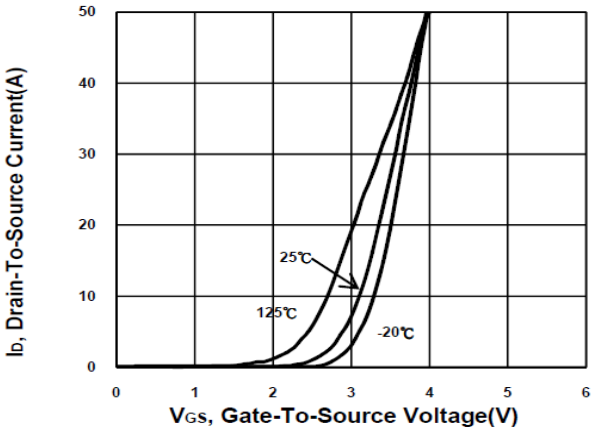
PD0903BVA

N-Channel Enhancement Mode MOSFET

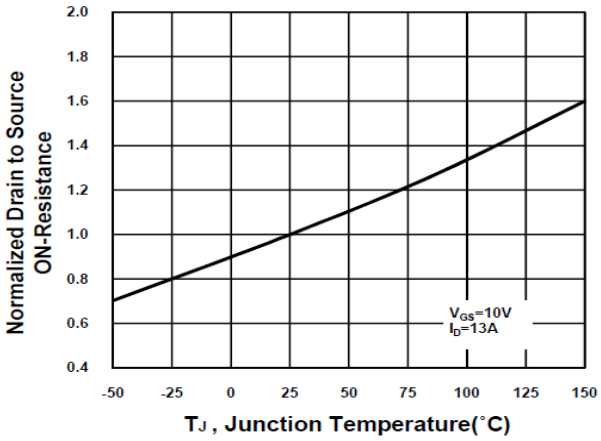
Output Characteristics



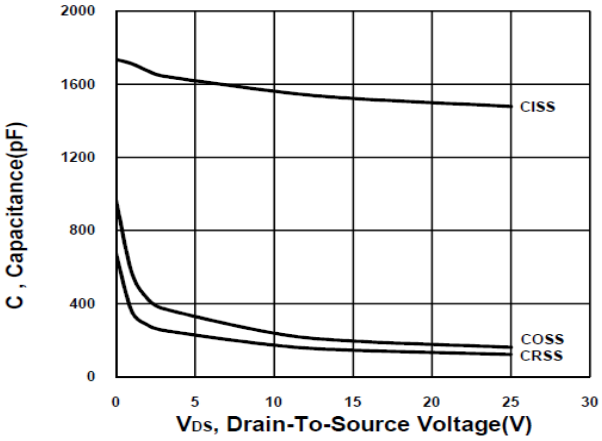
Transfer Characteristics



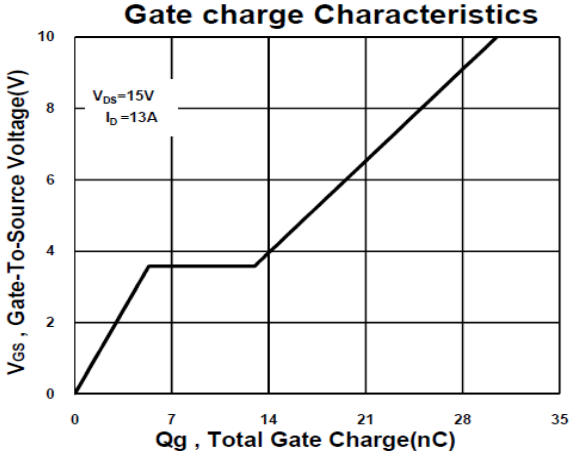
On-Resistance VS Temperature



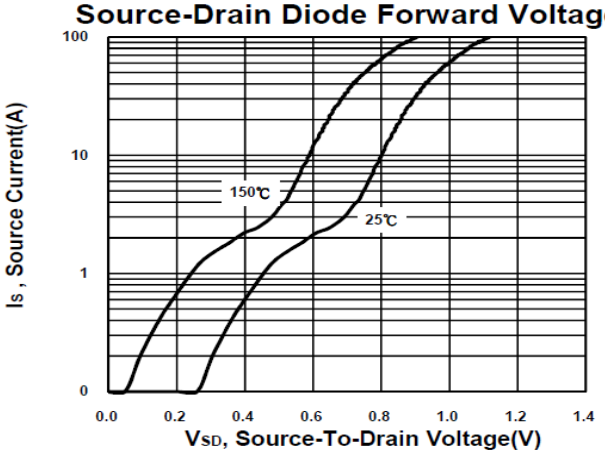
Capacitance Characteristic



Gate charge Characteristics



Source-Drain Diode Forward Voltage



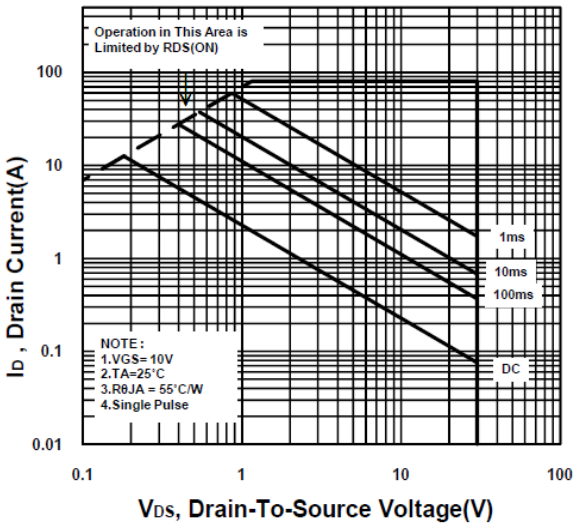
UNIKC Semiconductor

RoHS Compliant

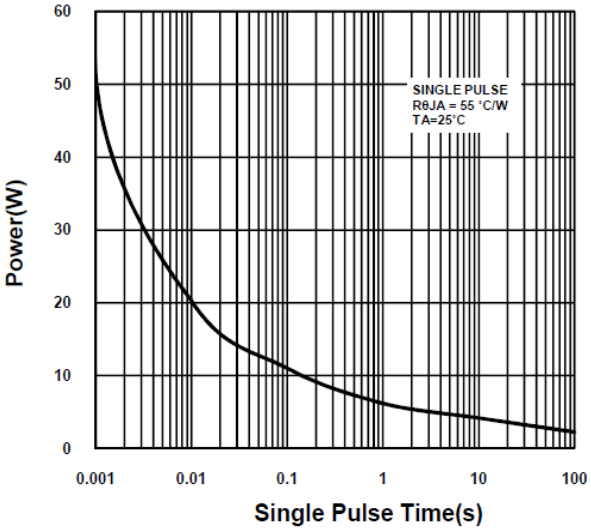
PD0903BVA

N-Channel Enhancement Mode MOSFET

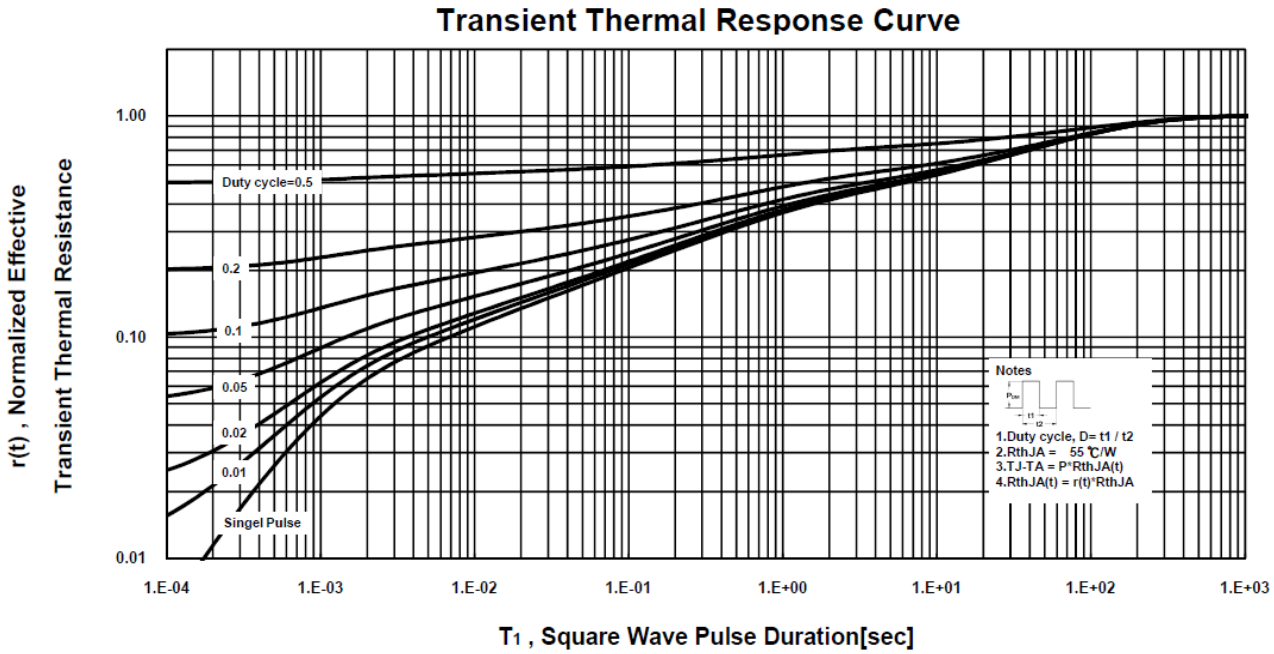
Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve



UNIKC Semiconductor

RoHS Compliant

PD0903BVA

N-Channel Enhancement Mode MOSFET

Package Dimension

SOP-8 MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.8	4.9	5.0	H	0.4	0.6	0.93
B	3.8	3.9	4.0	I	0.19	0.21	0.25
C	5.79	6.0	6.2	J	0.25	0.375	0.5
D	0.33	0.4	0.51	K	0°	3°	18°
E	1.25	1.27	1.29				
F	1.1	1.3	1.65				
G	0.05	0.15	0.25